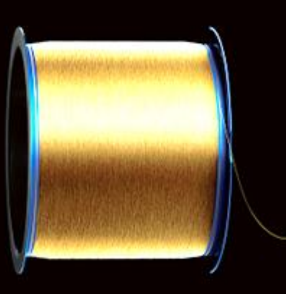


TANAKA's Bonding Wire

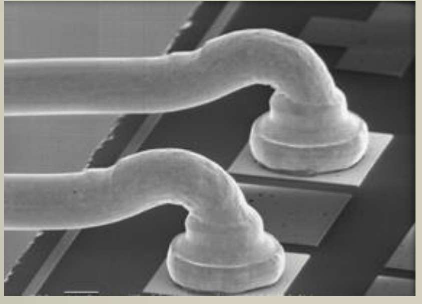
List of types

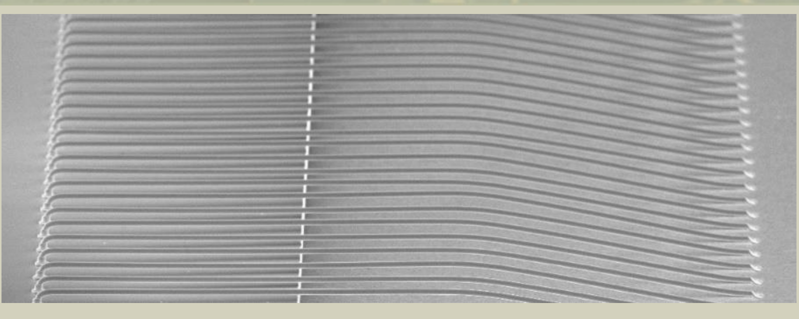
Type		Material: Gold	Material: Silver	Material: Copper	Material: Aluminum
Type	Fine Wire				
	Coated Fine Wire	TANAKA	TANAKA		TANAKA
	Thick Wire		Under Development		
	Ribbon		Under Development	Under Development	

Gold Bonding Wire

Characteristics

- Excellent bonding reliability
- Excellent bondability
- Wire diameter : Φ15 - 80μm

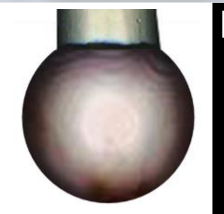


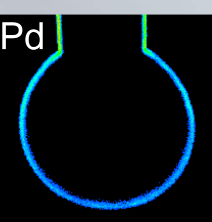


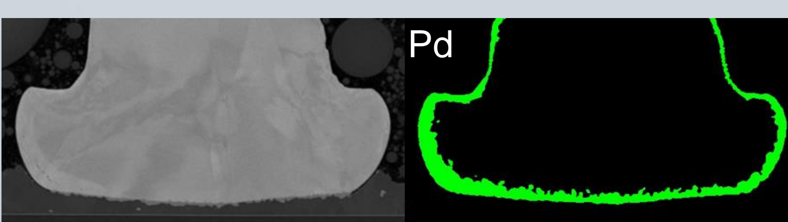
Palladium Coated Copper Wire

Characteristics

- Low cost (90% less than Gold Wire)
- Good bonding reliability
- Wire diameter : Φ15 - 80μm





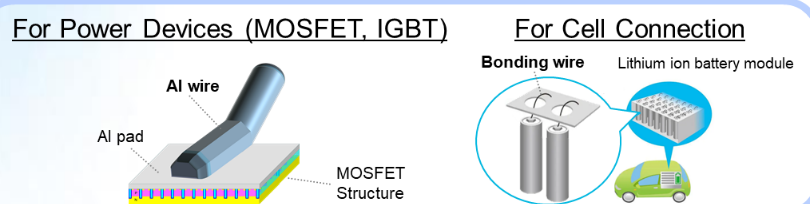


Aluminum Bonding Wire / TANW

Characteristics

- Excellent corrosion resistance.
- Excellent bondability.
- Wire diameter : Φ100 - 500μm
- Length : Max 800m (Φ300μm / No.88K)

(Φ300μm / No.88K)



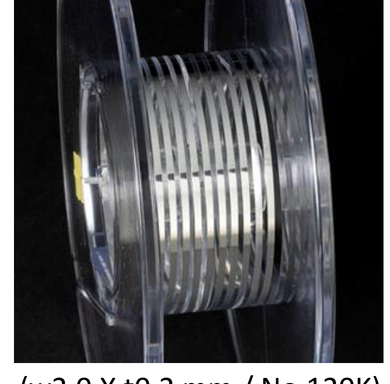
Looping image

Aluminum Bonding Ribbon / TABR

Available size

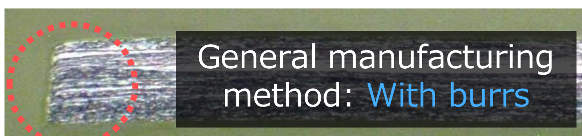
■ : Available size. ◆ : The product with Engineering spec only.

		Width [mm]					
		0.5	1.0	1.5	2.0	2.5	3.0
Thickness [mm]	0.10	■	■	■	■	■	■
	0.15		■	■	■		
	0.20		■	■	■		
	0.25			■	■		
	0.30			■	■		
	0.35						
	0.40				◆		



(w2.0 X t0.2 mm / No.120K)

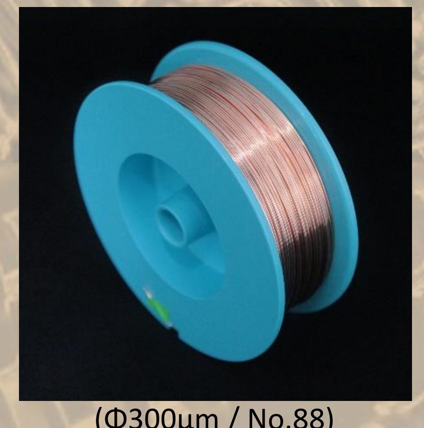
Product cross section



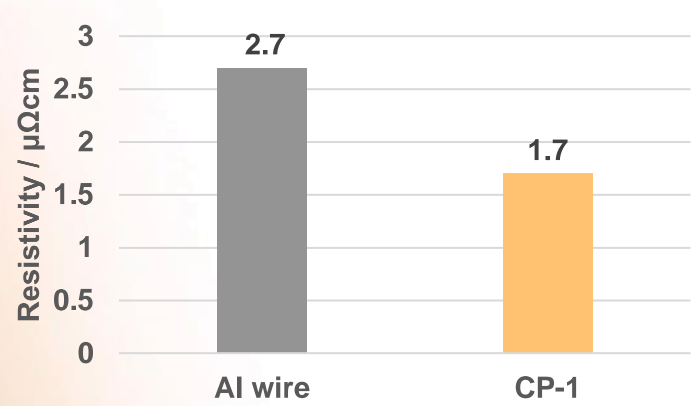
Copper Bonding Wire / CP-1

Characteristics

- Excellent electrical conductivity.
- High fusing current.
- Wire diameter : Φ100 - 500μm

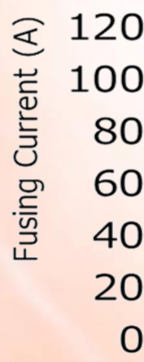

(Φ300μm / No.88)

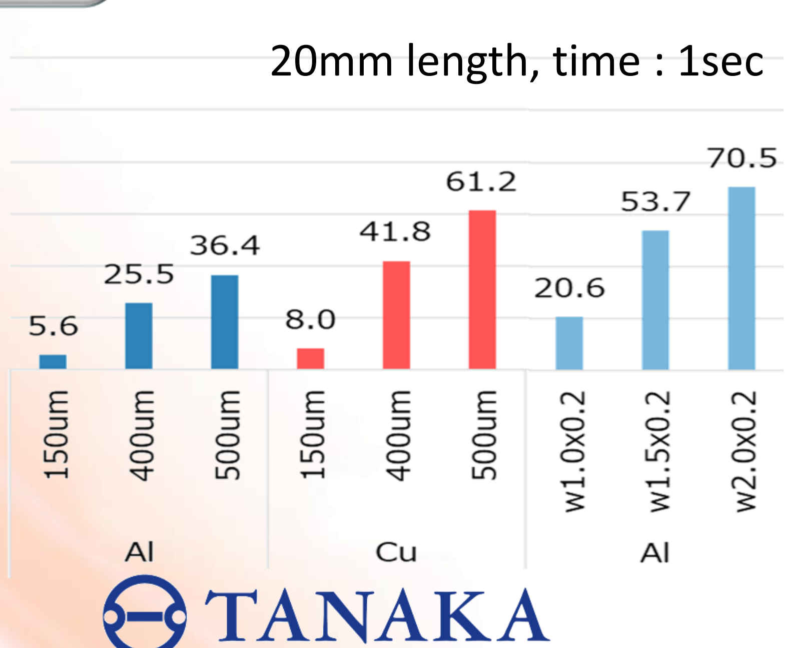
Resistivity



Looping image

Fusing current





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The Future is Precious.